

ZXMP6A16DN8

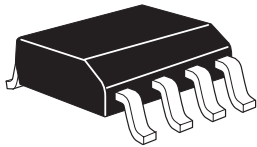
DUAL P-CHANNEL 60V ENHANCEMENT MODE MOSFET

SUMMARY

$V_{(BR)DSS} = -60V$; $R_{DS(ON)} = 0.085\Omega$; $I_D = -3.9A$

DESCRIPTION

This new generation of trench MOSFETs from Zetex utilizes a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, power management applications.



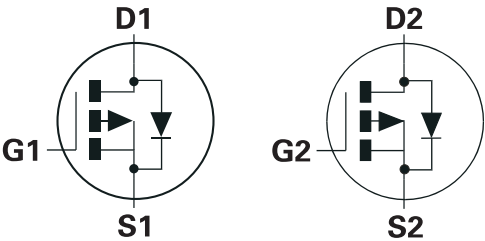
SO8

FEATURES

- Low on-resistance
- Fast switching speed
- Low threshold
- Low gate drive
- Low profile SOIC package

APPLICATIONS

- DC-DC converters
- Power management functions
- Disconnect switches
- Motor control



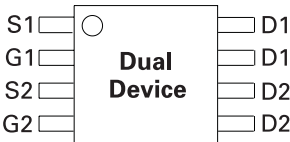
ORDERING INFORMATION

DEVICE	REEL	TAPE WIDTH	QUANTITY PER REEL
ZXMP6A16DN8TA	7"	12mm	500 units
ZXMP6A16DN8TC	13"	12mm	2500 units

DEVICE MARKING

ZXMP
6A16D

PINOUT



Top view

ZXMP6A16DN8

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DSS}	-60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current @ $V_{GS}=10V$; $T_A=25^\circ C$ ^{(b)(d)} @ $V_{GS}=10V$; $T_A=70^\circ C$ ^{(b)(d)} @ $V_{GS}=10V$; $T_A=25^\circ C$ ^{(a)(d)}	I_D	-3.9 -3.1 -2.9	A A A
Pulsed Drain Current ^(c)	I_{DM}	-18.3	A
Continuous Source Current (Body Diode) ^(b)	I_S	-3.2	A
Pulsed Source Current (Body Diode) ^(c)	I_{SM}	-18.3	A
Power Dissipation at $T_A=25^\circ C$ ^{(a)(d)} Linear Derating Factor	P_D	1.25 10	W mW/ $^\circ C$
Power Dissipation at $T_A=25^\circ C$ ^{(a)(e)} Linear Derating Factor	P_D	1.81 14.5	W mW/ $^\circ C$
Power Dissipation at $T_A=25^\circ C$ ^{(b)(d)} Linear Derating Factor	P_D	2.15 17	W mW/ $^\circ C$
Operating and Storage Temperature Range	$T_J:T_{stg}$	-55 to +150	$^\circ C$

THERMAL RESISTANCE

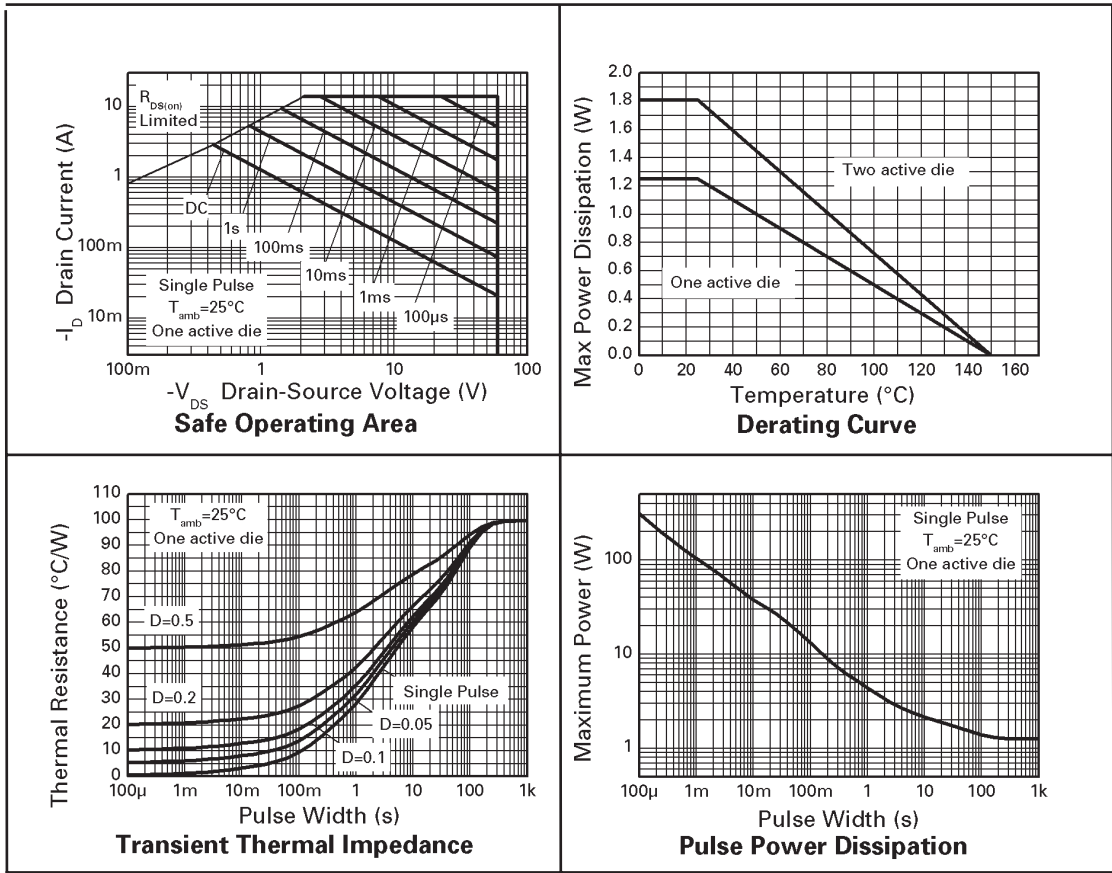
PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient ^{(a)(d)}	$R_{\theta JA}$	100	$^\circ C/W$
Junction to Ambient ^{(b)(e)}	$R_{\theta JA}$	70	$^\circ C/W$
Junction to Ambient ^{(b)(d)}	$R_{\theta JA}$	60	$^\circ C/W$

NOTES

- (a) For a dual device surface mounted on 25mm x 25mm FR4 PCB with coverage of single sided 1oz copper in still air conditions.
(b) For a dual device surface mounted on FR4 PCB measured at $t \leq 10$ sec.
(c) Repetitive rating 25mm x 25mm FR4 PCB, $D=0.05$ pulse width=300 μs - pulse width limited by maximum junction temperature.
(d) For a dual device with one active die.
(e) For dual device with 2 active die running at equal power.

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CHARACTERISTICS



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ELECTRICAL CHARACTERISTICS (at $T_{amb} = 25^{\circ}\text{C}$ unless otherwise stated)

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
STATIC						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	-60			V	I _D =-250μA, V _{GS} =0V
Zero Gate Voltage Drain Current	I _{DSS}			-1.0	μA	V _{DS} =-60V, V _{GS} =0V
Gate-Body Leakage	I _{GSS}			100	nA	V _{GS} =±20V, V _{DS} =0V
Gate-Source Threshold Voltage	V _{GS(th)}	-1.0			V	I _D =-250μA, V _{DS} = V _{GS}
Static Drain-Source On-State Resistance ⁽¹⁾	R _{DS(on)}			0.085 0.125	Ω Ω	V _{GS} =-10V, I _D =-2.9A V _{GS} =-4.5V, I _D =-2.4A
Forward Transconductance ⁽¹⁾⁽³⁾	g _{fs}		7.2		S	V _{DS} =-15V,I _D =-2.9A
DYNAMIC ⁽³⁾						
Input Capacitance	C _{iss}		1021		pF	V _{DS} =-30 V, V _{GS} =0V, f=1MHz
Output Capacitance	C _{Oss}		83.1		pF	
Reverse Transfer Capacitance	C _{rss}		56.4		pF	
SWITCHING ^{(2) (3)}						
Turn-On Delay Time	t _{d(on)}		3.5		ns	V _{DD} =-30V, I _D =-1A R _G ≅6.0Ω, V _{GS} =-10V
Rise Time	t _r		4.1		ns	
Turn-Off Delay Time	t _{d(off)}		35		ns	
Fall Time	t _f		10		ns	
Gate Charge	Q _g		12.1		nC	V _{DS} =-30V,V _{GS} =-5V, I _D =-2.9A
Total Gate Charge	Q _g		24.2		nC	V _{DS} =-30V,V _{GS} =-10V, I _D =-2.9A
Gate-Source Charge	Q _{gs}		2.5		nC	
Gate-Drain Charge	Q _{gd}		3.7		nC	
SOURCE-DRAIN DIODE						
Diode Forward Voltage ⁽¹⁾	V _{SD}		-0.85	-0.95	V	T _J =25°C, I _S =-3.4A, V _{GS} =0V
Reverse Recovery Time ⁽³⁾	t _{rr}		29.2		ns	T _J =25°C, I _F =-2A, di/dt= 100A/μs
Reverse Recovery Charge ⁽³⁾	Q _{rr}		39.6		nC	

NOTES

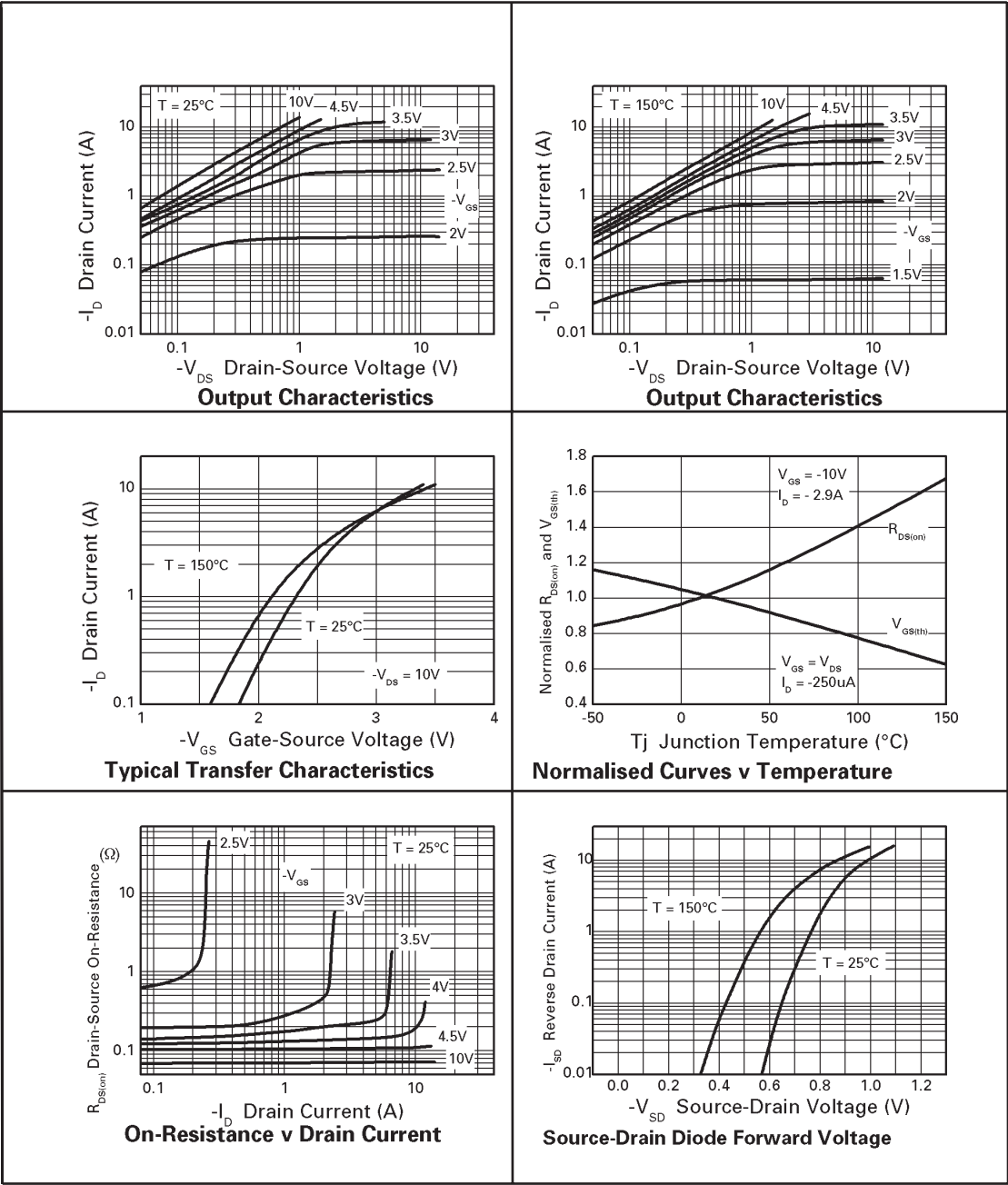
(1) Measured under pulsed conditions. Width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.

(2) Switching characteristics are independent of operating junction temperature.

(3) For design aid only, not subject to production testing.

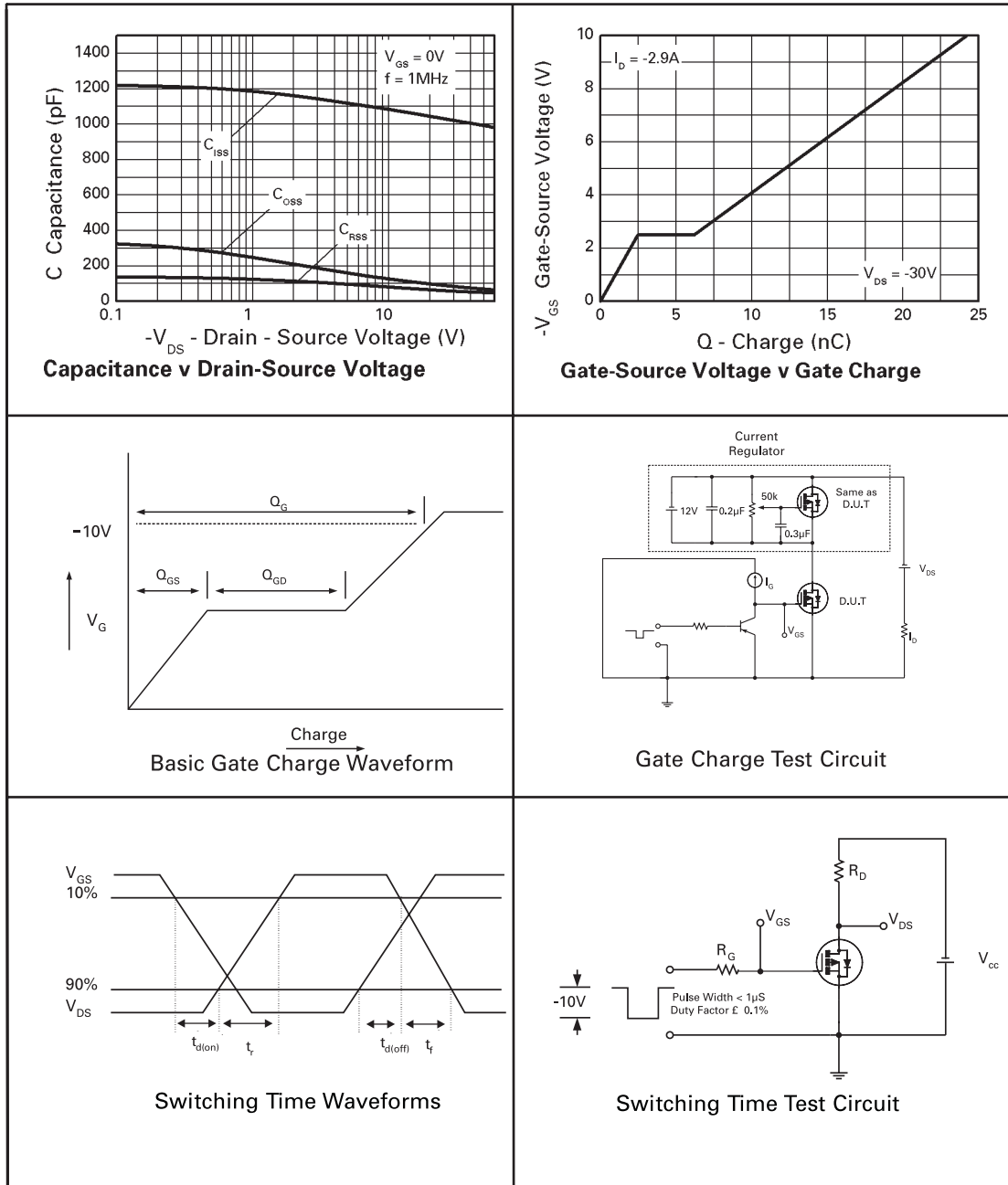
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TYPICAL CHARACTERISTICS



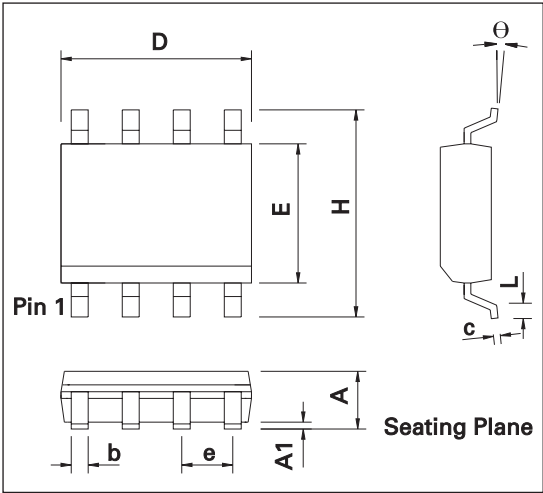
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TYPICAL CHARACTERISTICS



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PACKAGE OUTLINE



CONTROLLING DIMENSIONS ARE IN INCHES
APPROX IN MILLIMETERS

PACKAGE DIMENSIONS

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min	Max	Min	Max		Min	Max	Min	Max
A	1.35	1.75	0.053	0.069	e	1.27 BSC		0.050 BSC	
A1	0.10	0.25	0.004	0.010	b	0.33	0.51	0.013	0.020
D	4.80	5.00	0.189	0.197	c	0.19	0.25	0.008	0.010
H	5.80	6.20	0.228	0.244	Θ	0°	8°	0°	8°
E	3.80	4.00	0.150	0.157	h	0.25	0.50	0.010	0.020
L	0.40	1.27	0.016	0.050	-	-	-	-	-

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